



AMTECH

Advanced SMT Solder Products

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VS-213-TF, No-Clean Tacky Flux

Product Data Sheet

Product Highlights

- ROLO flux classification
- Optimized for Lead-free and standard alloy systems
- Designed for LGA, BGA, and CSP components
- Halogen free per EN14582 test method
- Excellent wetting on all common surface finishes
- Clear residue
- Low voiding
- REACH compliant

Application

VS-213-TF is formulated for syringe, stencil printing, and rework applications on all PCB surface finishes. VS-213-TF may be used for BGA sphere attachment and reballing. VS-213-TF is also designed to work on all flip chip bumping and chip scale packaging sites.

Compatible Alloys

Alloy	Temp °C	Temp °F
63Sn/37Pb	183	361
62Sn/36Pb/2Ag	179	354
62.8Sn/36.8Pb/0.4Ag	179-183	354-361
42Sn/58Bi	138	280
42Sn/57Bi/1Ag	138	280
96.5Sn/3.0Ag/0.5Cu	217-220	423-428
99.0Sn/0.3Ag/0.7Cu	217-221	423-430
96.5Sn/3.5Ag	221	430
99.3Sn/0.7Cu	227	441
95Sn/5Sb	235-240	455-464
95Sn/5Ag	221-245	430-473

Test Results

Test J-STD-004 or other requirements (as stated)	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (no-clean)
Surface Insulation Resistance 85 °C, 85% RH@ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100 MΩ (No-clean)
Viscosity - Malcom @ 10 RPM/25 °C (x10 ³ mPa/s)	IPC-TM-650: 2.4.34.4	40-65
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

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Cleaning

VS-213-TF is a no clean tacky flux that can be left on the board for many SMT assemblies. For applications requiring cleaning, VS-213-TF can be cleaned using commercially available flux residue removers such as Kyzen Aquanox A4241, A4520, A4625 and A4625B (Batch Cleaners). Kyzen brand cleaners are available from Amtech.

Storage and Handling

Tacky flux should be stored at room temperature (20-25 °C). Syringes and cartridges should be stored vertically with the dispensing tip down. Properly stored tacky flux has a 12 month shelf life.

Packaging

- 10 & 30cc syringes
- 75 & 150 gram jars
- 170 & 340 gram cartridges

Recommended Profile

This profile is designed to serve as a starting point for process optimization using VS-213-TF. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <60 seconds.

